

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	248	(chip die (semiconductor near1 (element device package)) ic) same ceramic same (substrate ((circuit wiring printed) near1 board)) same adhesive same ((metal bonding bond) near pad)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 09:34
L2	240	1 and (method process)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 09:35
L3	132	2 and (cavity aperture)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 09:42
L5	4970	257/697,700,701,704-705.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 09:37
L6	11	3 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 09:37
L7	121	3 not 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 09:42
L8	4583	438/51,64,106,125.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 10:26
L9	6	3 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 10:26